



Dear IEEE IES Students and Young Professionals (S&YP),

Congratulations! It is our great pleasure to announce the Awardees of the IES-SYPA competition for the IEEE ICIT 2019.

Important note for the S&YP that applied for the IES-SYPA:

IEEE ICIT2019 has received **20** applications for the IEEE IES STUDENT & YOUNG PROFESSIONALS PAPER ASSISTANCE (IES-SYPA). The average weighted score is **7.09.** We would like to announce the **10 IES-SYPA** (recognition diploma plus up-to **USD 2000** travel costs reimbursement) recipients (refer to the table below).

Transaction	Applicant	Manuscript title	All Authors
MF-014869	Andrii Chub, Federico Santa Maria Technical University, Chile, andrii.chub@usm.cl	Wide Input Voltage Range High Step-Up DC-DC Converter with Fault-Tolerant Operation Capability	Dmitri Vinnikov, Andrii Chub, Oleksandr Korkh, Samir Kouro
MF-009555	Anubrata Das, PhD Scholar, India, anubrata0103@gmail.com	Method to Reduce Harmonic Voltage Distortion and Improve Harmonic Current Sharing in an islanded AC Microgrid	Ankit Shukla, Anubrata Das, Sandeep Anand
MF-013412	Maryam Sarebanzadeh, University of Talca, Chile, maryam_sarbanzadeh@yahoo.com	Model Predictive Control for the New Reduced Multi-level Grid-Connected Converter	Maryam Sarebanzadeh, Mohammad Hosseinzadeh, Ali Salehi, Marco Rivera, Javier Munoz, Patrick Wheeler
MF-011274	Hector R Robles-Campos, University of Colorado Denver, USA, hector.robles@ucdenver.edu	A comparative evaluation of modulation strategies for Hexverter-based Modular Multilevel Converters	Hector R Robles-Campos, Fernando Mancilla-David
MF-012939	Iram Jaffar, Quaid-i-Azam University, Pakistan, ijaffar@ir.qau.edu.pk	Security Hardening for Implantable Cardioverter Defibrillators	Iram Jaffar, Muhammad Usman, Alireza Jolfaei
MF-004464	Mahdi Soltani, Electrical engineering and energy technology (ETEC) department, MOBI Research Group, Vrije Universiteit Brussel, Belgium, mahdi.soltani@vub.be	Three-dimensional thermal model for a commercial Lithium-ion Capacitor battery pack with non-uniform temperature distribution	Mahdi Soltani, Jan Ronsmans, Joris Jaguemont, Joeri Van Mierlo, Peter Van den Bossche, Noshin Omar
MF-008931	Sangdae Kim, Chungnam National University, Korea (South), sdkim@cclab.cnu.ac.kr	Routing Graph Management for Mobility Support in Industrial Wireless Sensor Networks	Sangdae Kim, Cheonyong Kim, Hyunchong Cho, Taehun Yang, Sang-Ha Kim, Kwansoo Jung
MF-003816	Dilini Jayananda, University of Waikato, New Zealand (Aotearoa), dukju1@students.waikato.ac.nz	Performance Characteristics of Energy- Efficient LED Lamps Leading to Supercapacitor Assisted LED (SCALED) Technique for DC-Microgrid Applications	Dilini Jayananda, Nihal Kularatna, D.Alistair Steyn-Ross
MF-013129	Mohammad Ali Hosseinzadeh, Universidad de Talca, Chile, m.a_hosseinzadeh@yahoo.com	New Reduced Switched Multilevel Inverter for Three-Phase Grid- Connected PV System: Performance Evaluation	Mohammad Ali Hosseinzadeh, Maryam Sarbanzadeh, Javier Muńoz, Marco Rivera, Carlos Muńoz, Ariel Villalon
MF-009881	Fan Feng, Nanyang Technological University, Singapore, ffeng003@e.ntu.edu.sg	Stability Analysis and Optimization of Dual Active Bridge Converter with LC Input Filter	Fan Feng, Xin Zhang, Fanfan Lin, Hoay Beng Gooi

Mandatory requirements and important notes:

I. Please take into account that IEEE IES must follow general rules of IEEE related with OFAC Sanctions (https://www.ieee.org/about/compliance/ofac/sanctions.html). For more details, you may ask The Legal and Compliance Department available to assist with reviewing any questions that you may have with respect to OFAC or other compliance matters that can be reached at compliance@ieee.org.





- II. You will have to be active during the conference as a volunteer. For tasks and more details, please contact Secretary of ICIT at: theni@laevents.com.au, with CC. to Prof. Yousef Ibrahim, Gen. Chair, ICIT 2019 at: yousef.ibrahim@ieee.org and to marek.jasinski@ieee.org.
- III. **Students** and **Young Professionals** have to present their project in a 3-minutes speech (3Ms) with hardware demonstration (if applicable) or video clip.
- IV. Please send the declaration and confirmation that you will email a 3 minutes movie and speech to Hani Vahedi (hani.vahedi@ieee.org) and Marek Jasinski (gold.ies.ieee.chair@gmail.com) as soon as possible, but not later than 10.01.2019.
- V. You will then receive the full instructions on how to prepare that movie and speech for 3Ms IES-SYPA Speech Video Session.
- VI. Your video will be uploaded on IES YouTube Channel, Facebook Page, and IEEE Collabratec to be available during the conference. Important:
 - a. Please open an IEEE Collabratec account with your IEEE login information.
 - b. For the confirmation, please send to hani.vahedi@ieee.org your IEEE Collabratec username email.
 - c. You will be added to the IES-SYPA Group.
 - d. Once your video is approved and uploaded to the IES YouTube, then you should post it to the IEEE Collabratec Group and to the Facebook event page.
- VII. Please make sure that during the conference **you will have your video available off-line** and the hardware demonstration (if applicable).
 - (Time and place for 3Ms presentation will be announced by the General Chair of the Conference)
- VIII. The diplomas for the IES-Student Paper Travel Assistance (IES-SYPA) will be presented during the conference.
 - (Time and place will be announced by the General Chair of the Conference usually Gala Dinner)
- IX. Take photos during the conference and submit them on your and IES Facebook profile.
- X. Submit your expenses report and chose the IES-SYPA payment method (wire transfer or cheque).

 All documents have to be sent to:
 - IES Treasurer Milos Manic: treasurer@ieee-ies.org, misko@ieee.org
 - with CC to the Chair of the SYP Activity Committee Marek Jasinski: gold.ies.ieee.chair@gmail.com.
- XI. PLEAS NOTE THAT IEEE IES STUDENT & YOUNG PROFESSIONALS PAPER ASSISTANCE consists of:
 - Recognition Diploma and
 - up to USD 2000 travel cost reimbursements.
- XII. You can find all the necessary information on Industry Electronics Society websites:
 - https://www.facebook.com/IndustrialElectronicsSociety/
 - http://www.ieee-ies.org/SYP
- XIII. Instruction for travel reimbursements can be found at:
 - http://www.ieee-ies.org/members/treasurer-information





Please fill in the following documents:

- Single or Multi-Currency Expense Report Form
- Wire Transfer Request Form
- Remember to send in pdf your invoices and receipts from, e.g. hotel, airplane, conference fee, taxi, bus, train, meals

On behalf of the IEEE IES-SYPA Competition Jury:

IEEE IES President Xinghuo Yu, IES Treasurer Milos Manic, and IES President Elect Terry Martin
Vice President for Conference Activities Juan José Rodríguez Andina
Vice President for Membership Activities Yousef Ibrahim
Conference General Chairs: Yousef Ibrahim, Juan Jose R. Andina, Xinghuo Yu
Web & Information Committee: Andres A. Nogueiras Melendez, Aleksander Malinowski
Ad-Hoc committee related to IEEE OFAC Sanctions Programs:
Gus Wagner Director, Technical Activities Operations and Society Support Services IEEE Technical Activities
Matt LaFleur Technical Community Program Coordinator IEEE Technical Activities
and Young Professional & Student Activity Committee: Marek Turzynski, Hani Vahedi, Marek Jasinski

Congratulations and Good Luck, Chair of the IEEE IES Young Professional & Student Activity Committee, Marek Jasinski